





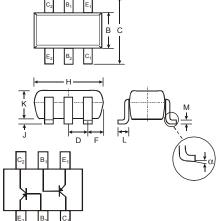
DUAL PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- **Epitaxial Planar Die Construction**
- Ideal for Low Power Amplification and Switching
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 3)
- "Green" Device (Note 4 and 5)

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Terminal Connections: See Diagram
- Marking Information: K2T See Page 4
- Ordering & Date Code Information: See Page 4
- Weight: 0.006 grams (approximate)



	SOT-363										
Dim	Min	Max									
Α	0.10	0.30									
В	1.15	1.35									
С	2.00	2.20									
D	0.65 N	ominal									
F	0.30	0.40									
Н	1.80	2.20									
J	_	0.10									
K	0.90	1.00									
L	0.25	0.40									
М	0.10	0.25									
α	0°	8°									
All Din	nensions	in mm									

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Collector-Base Voltage		V_{CBO}	-40	V
Collector-Emitter Voltage		V_{CEO}	-40	V
Emitter-Base Voltage		V_{EBO}	-5.0	V
Collector Current - Continuous	(Note 1)	Ic	-600	mA
Power Dissipation	(Note 1, 2)	P_d	200	mW
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range		T _i , T _{STG}	-55 to +150	°C

Notes:

- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- Maximum combined dissipation.
- No purposefully added lead.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

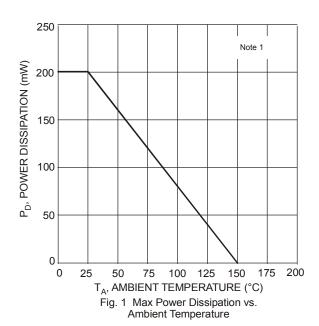
 Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

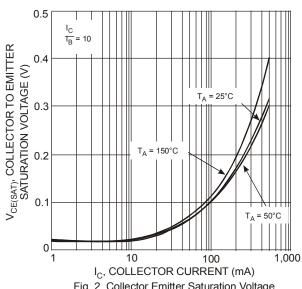


Electrical Characteristics @T_A = 25°C unless otherwise specified

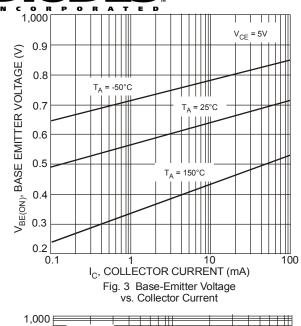
Characteristic	Symbol	Min	Max	Unit	Test Condition			
OFF CHARACTERISTICS (Note 6)								
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-40		V	$I_C = -100 \mu A, I_E = 0$			
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	-40		V	$I_C = -1.0 \text{mA}, I_B = 0$			
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-5.0		٧	$I_E = -100 \mu A, I_C = 0$			
Collector Cutoff Current	I _{CEX}		-100	nA	$V_{CE} = -35V, V_{EB(OFF)} = -0.4V$			
Base Cutoff Current	I _{BL}		-100	nA	$V_{CE} = -35V, V_{EB(OFF)} = -0.4V$			
ON CHARACTERISTICS (Note 6)								
DC Current Gain	h _{FE}	30 60 100 100 20	 300 		$\begin{split} I_{C} &= -100 \mu A, V_{CE} = -1.0 V \\ I_{C} &= -1.0 m A, V_{CE} = -1.0 V \\ I_{C} &= -10 m A, V_{CE} = -1.0 V \\ I_{C} &= -150 m A, V_{CE} = -2.0 V \\ I_{C} &= -500 m A, V_{CE} = -2.0 V \end{split}$			
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	-0.40 -0.75	٧	I_C = -150mA, I_B = -15mA I_C = -500mA, I_B = -50mA			
Base-Emitter Saturation Voltage		-0.75 —	-0.95 -1.30	٧	I_C = -150mA, I_B = -15mA I_C = -500mA, I_B = -50mA			
SMALL SIGNAL CHARACTERISTICS								
Output Capacitance	C_{cb}	_	8.5	pF	$V_{CB} = -10V$, $f = 1.0MHz$, $I_E = 0$			
Input Capacitance	C _{eb}	_	30	pF	$V_{EB} = -0.5V$, $f = 1.0MHz$, $I_{C} = 0$			
Input Impedance	h _{ie}	1.5	15	kΩ				
Voltage Feedback Ratio	h _{re}	0.1	8.0	x 10 ⁻⁴	$V_{CE} = -10V, I_{C} = -1.0mA,$			
Small Signal Current Gain	h _{fe}	60	500		f = 1.0kHz			
Output Admittance	h _{oe}	1.0	100	μS				
Current Gain-Bandwidth Product	f _T	200		MHz	V _{CE} = -10V, I _C = -20mA, f = 100MHz			
SWITCHING CHARACTERISTICS								
Delay Time	t _d	_	15	ns	$V_{CC} = -30V, I_{C} = -150mA,$			
Rise Time	t _r	_	20	ns	$V_{BE(off)} = -2.0V, I_{B1} = -15mA$			
Storage Time	ts	_	225	ns	$V_{CC} = -30V, I_{C} = -150mA,$			
Fall Time	t _f	_	30	ns	$I_{B1} = I_{B2} = -15\text{mA}$			

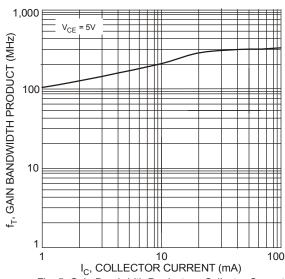
Notes: 6. Short duration pulse test used to minimize self-heating effect.



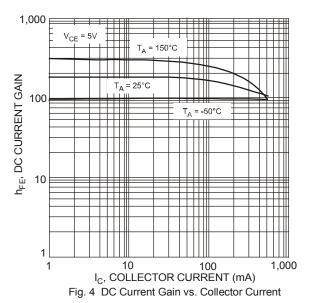


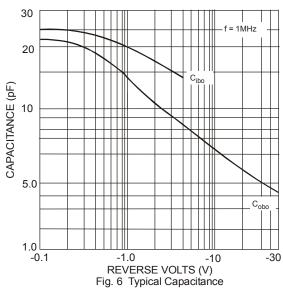


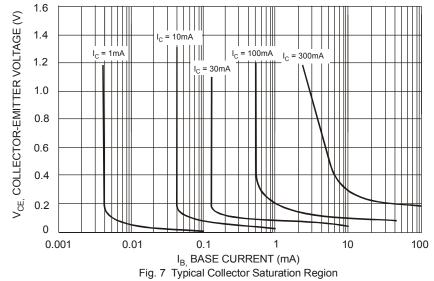












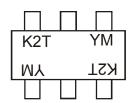


Ordering Information (Note 7)

Device	Packaging	Shipping		
MMDT4403-7-F	SOT-363	3000/Tape & Reel		

7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



K2T = Product Type Marking Code YM = Date Code Marking Y = Year ex: N = 2002 M = Month ex: 9 = September

Date Code Key

ĺ	Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
	Code	J	K	L	М	N	Р	R	S	Т	U	V	W	Х	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

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